

# E4M0060075K1

Silicon Carbide Power MOSFET  
E-Series Automotive  
N-Channel Enhancement Mode

## Features

- Optimized package with separate driver source pin
- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery ( $Q_{rr}$ )
- Halogen free, RoHS compliant
- Automotive Qualified (AEC-Q101) and PPAP Capable

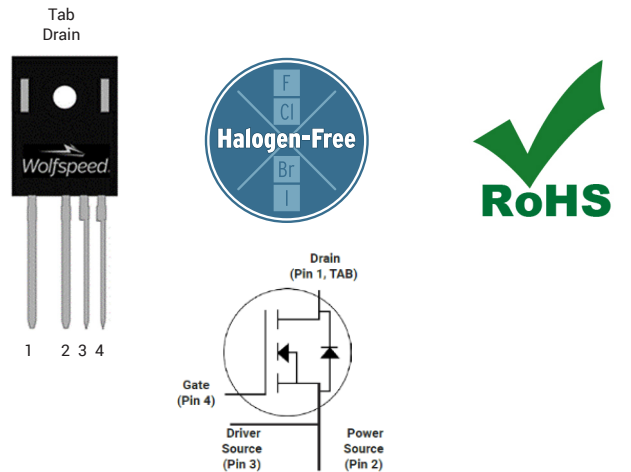
## Benefits

- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency

## Applications

- Motor Control
- EV Battery Chargers
- High Voltage DC/DC Converters

## Package



Part Number	Package	Marking
E4M0060075K1	TO-247-4L	E4M0060075K1

## Maximum Ratings ( $T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit	Note
$V_{DSmax}$	Drain - Source Voltage	750	V	
$V_{GSmax}$	Gate - Source Voltage	-8/+19	V	Note: 1
$I_D$	Continuous Drain Current, $V_{GS} = 15\text{ V}$	$T_c = 25^\circ\text{C}$	35	A Fig. 19 Note: 2
		$T_c = 100^\circ\text{C}$	26	
$I_{D(pulse)}$	Pulsed Drain Current, Pulse width $t_p$ limited by $T_{jmax}$	101	A	Fig. 22
$P_D$	Power Dissipation, $T_c=25^\circ\text{C}$ , $T_j = 175^\circ\text{C}$	126	W	Fig. 20 Note: 2
$T_j, T_{stg}$	Operating Junction and Storage Temperature	-55 to +175	$^\circ\text{C}$	
$T_L$	Solder Temperature, 1.6mm (0.063") from case for 10s	260	$^\circ\text{C}$	
$M_d$	Mounting Torque, M3 or 6-32 screw	1	Nm	
		8.8	lbf-in	

Note (1): Recommended turn off / turn on gate voltage  $V_{GS} = -4V..0V / +15V$

Note (2): Verified by design


**Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	750			V	$V_{GS} = 0\text{ V}, I_D = 100\text{ }\mu\text{A}$	
$V_{GS(th)}$	Gate Threshold Voltage	1.8	2.6	3.8	V	$V_{DS} = V_{GS}, I_D = 3.67\text{ mA}$	Fig. 11
			2.1		V	$V_{DS} = V_{GS}, I_D = 3.67\text{ mA}, T_J = 175^\circ\text{C}$	
$I_{DSS}$	Zero Gate Voltage Drain Current		1	50	$\mu\text{A}$	$V_{DS} = 750\text{ V}, V_{GS} = 0\text{ V}$	
$I_{GSS}$	Gate-Source Leakage Current		10	250	nA	$V_{GS} = 15\text{ V}, V_{DS} = 0\text{ V}$	
$R_{DS(on)}$	Drain-Source On-State Resistance		60	78	m $\Omega$	$V_{GS} = 15\text{ V}, I_D = 13.4\text{ A}$	Fig. 4, 5, 6
			87			$V_{GS} = 15\text{ V}, I_D = 13.4\text{ A}, T_J = 175^\circ\text{C}$	
$g_{fs}$	Transconductance		10		S	$V_{DS} = 20\text{ V}, I_{DS} = 13.4\text{ A}$	Fig. 7
			8			$V_{DS} = 20\text{ V}, I_{DS} = 13.4\text{ A}, T_J = 175^\circ\text{C}$	
$C_{iss}$	Input Capacitance		1203		pF	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V to } 500\text{ V}$ $F = 100\text{ kHz}$ $V_{AC} = 25\text{ mV}$	Fig. 17, 18
$C_{oss}$	Output Capacitance		69				
$C_{rss}$	Reverse Transfer Capacitance		7				
$E_{oss}$	$C_{oss}$ Stored Energy		10		$\mu\text{J}$		Fig. 16
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		90		pF	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{... } 500\text{ V}$	Note: 3
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		129		pF		
$E_{ON}$	Turn-On Switching Energy (External Diode)		52		$\mu\text{J}$	$V_{DS} = 500\text{ V}, V_{GS} = -4\text{ V/}15\text{ V}, I_D = 13.4\text{ A},$ $R_{G(ext)} = 2.5\text{ }\Omega, L = 135\text{ }\mu\text{H}, T_J = 175^\circ\text{C}$ FWD = External SiC DIODE	Fig. 26, 28
$E_{OFF}$	Turn Off Switching Energy (External Diode)		16				
$E_{ON}$	Turn-On Switching Energy (Body Diode FWD)		56		$\mu\text{J}$	$V_{DS} = 500\text{ V}, V_{GS} = -4\text{ V/}15\text{ V}, I_D = 13.4\text{ A},$ $R_{G(ext)} = 2.5\text{ }\Omega, L = 135\text{ }\mu\text{H}, T_J = 175^\circ\text{C}$ FWD = Internal Body Diode	Fig. 26, 28
$E_{OFF}$	Turn-Off Switching Energy (Body Diode FWD)		16				
$t_{d(on)}$	Turn-On Delay Time		8		ns	$V_{DD} = 500\text{ V}, V_{GS} = -4\text{ V/}15\text{ V}$ $I_D = 13.4\text{ A}, R_{G(ext)} = 2.5\text{ }\Omega, L = 135\text{ }\mu\text{H}$ Timing relative to $V_{DS}$ Inductive load	Fig. 27, 28
$t_r$	Rise Time		9				
$t_{d(off)}$	Turn-Off Delay Time		16				
$t_f$	Fall Time		9				
$R_{G(int)}$	Internal Gate Resistance		3.0		$\Omega$	$f = 1\text{ MHz}, V_{AC} = 25\text{ mV}$	
$Q_{gs}$	Gate to Source Charge		14		nC	$V_{DS} = 500\text{ V}, V_{GS} = -4\text{ V/}15\text{ V}$ $I_D = 13.4\text{ A}$ Per IEC60747-8-4 pg 21	Fig. 12
$Q_{gd}$	Gate to Drain Charge		18				
$Q_g$	Total Gate Charge		52				

Note (3):  $C_{o(er)}$ , a lumped capacitance that gives same stored energy as  $C_{oss}$  while  $V_{ds}$  is rising from 0 to 500V

$C_{o(tr)}$ , a lumped capacitance that gives same charging time as  $C_{oss}$  while  $V_{ds}$  is rising from 0 to 500V

Reverse Diode Characteristics (T<sub>c</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V <sub>SD</sub>	Diode Forward Voltage	4.8		V	V <sub>GS</sub> = -4 V, I <sub>SD</sub> = 6.7 A, T <sub>J</sub> = 25 °C	Fig. 8, 9, 10
		4.2		V	V <sub>GS</sub> = -4 V, I <sub>SD</sub> = 6.7 A, T <sub>J</sub> = 175 °C	
I <sub>S</sub>	Continuous Diode Forward Current		22	A	V <sub>GS</sub> = -4 V, T <sub>c</sub> = 25°C	
I <sub>S, pulse</sub>	Diode pulse Current		101	A	V <sub>GS</sub> = -4 V, pulse width t <sub>p</sub> limited by T <sub>Jmax</sub>	
t <sub>rr</sub>	Reverse Recovery time	14		ns	V <sub>GS</sub> = -4 V, I <sub>SD</sub> = 13.4 A, V <sub>R</sub> = 500 V dif/dt = 6160 A/μs, T <sub>J</sub> = 175 °C	
Q <sub>rr</sub>	Reverse Recovery Charge	327		nC		
I <sub>rrm</sub>	Peak Reverse Recovery Current	40		A		
t <sub>rr</sub>	Reverse Recovery time	23		ns	V <sub>GS</sub> = -4 V, I <sub>SD</sub> = 13.4 A, V <sub>R</sub> = 500 V dif/dt = 2150 A/μs, T <sub>J</sub> = 175 °C	
Q <sub>rr</sub>	Reverse Recovery Charge	220		nC		
I <sub>rrm</sub>	Peak Reverse Recovery Current	18		A		

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
R <sub>θJC</sub>	Thermal Resistance from Junction to Case	0.91	1.19	°C/W		Fig. 21



## Typical Performance

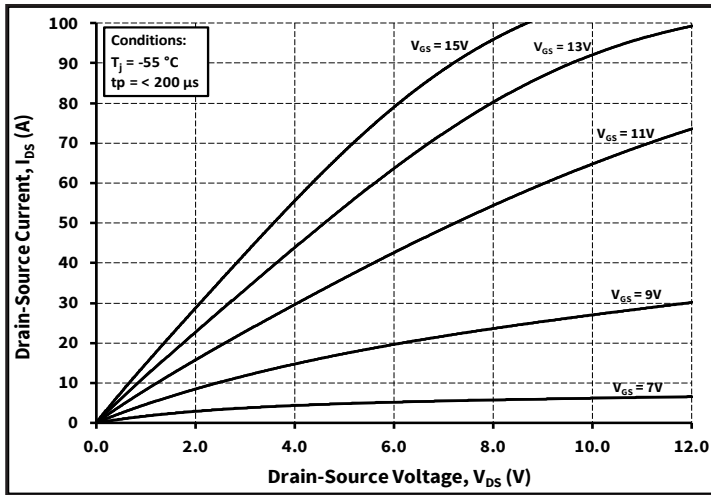


Figure 1. Output Characteristics  $T_J = -55\text{ }^{\circ}\text{C}$

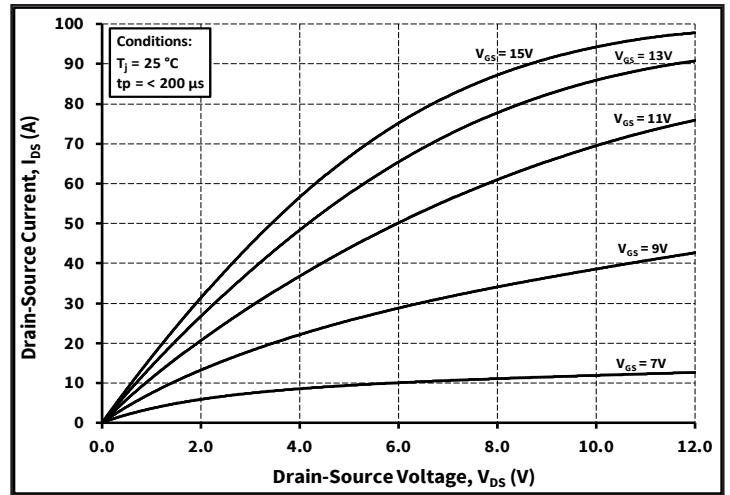


Figure 2. Output Characteristics  $T_J = 25\text{ }^{\circ}\text{C}$

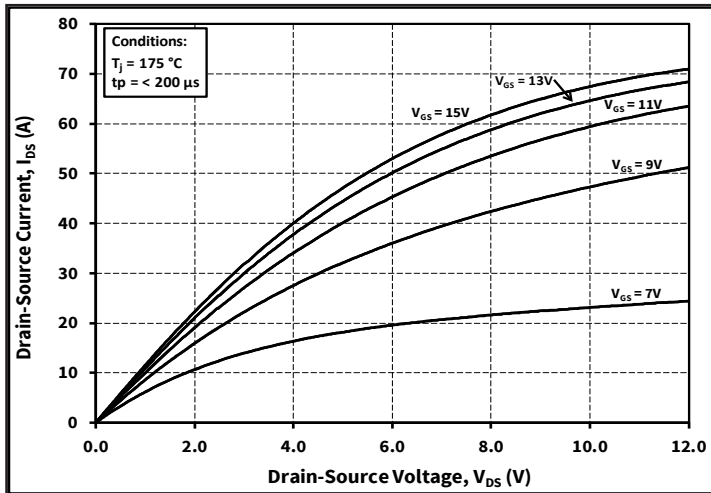


Figure 3. Output Characteristics  $T_J = 175\text{ }^{\circ}\text{C}$

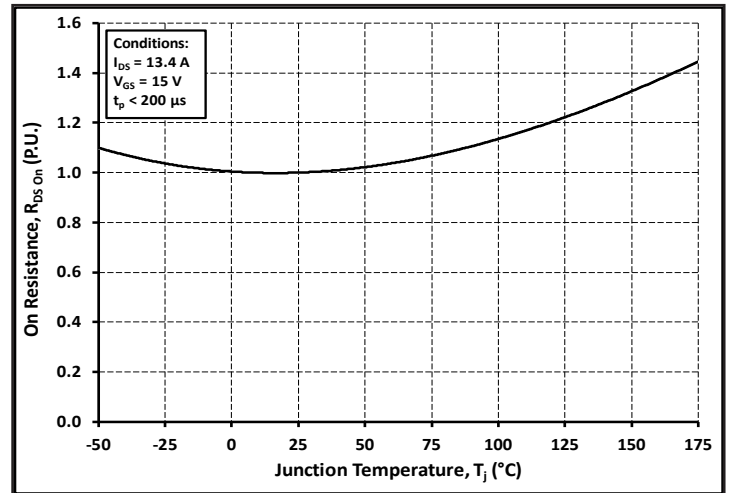


Figure 4. Normalized On-Resistance vs. Temperature

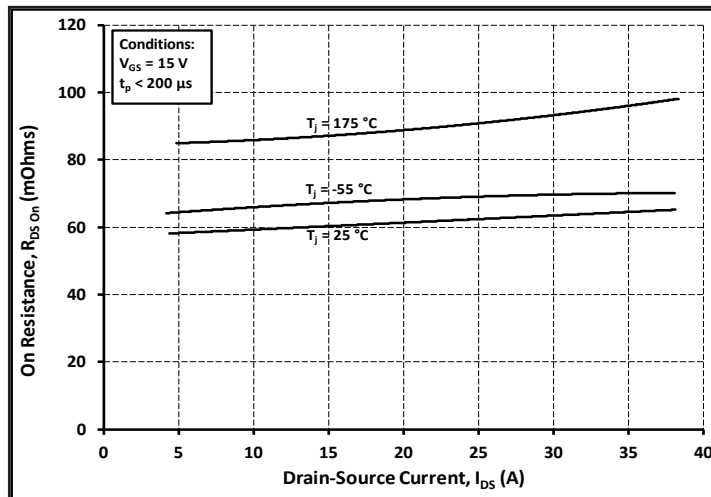


Figure 5. On-Resistance vs. Drain Current  
For Various Temperatures

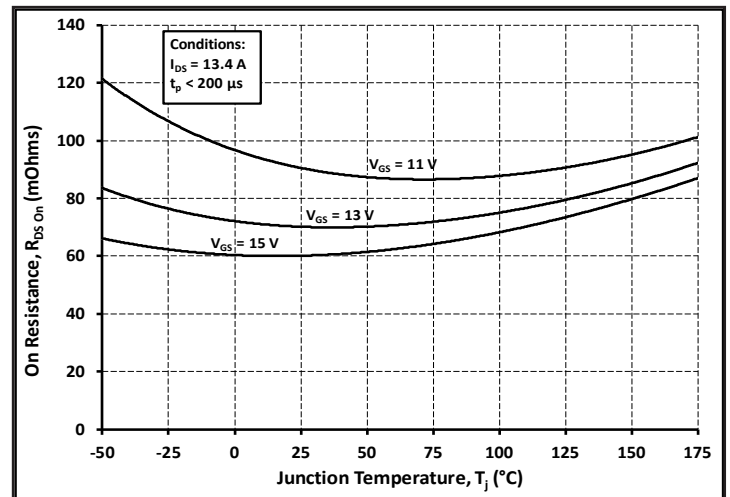


Figure 6. On-Resistance vs. Temperature  
For Various Gate Voltage

## Typical Performance

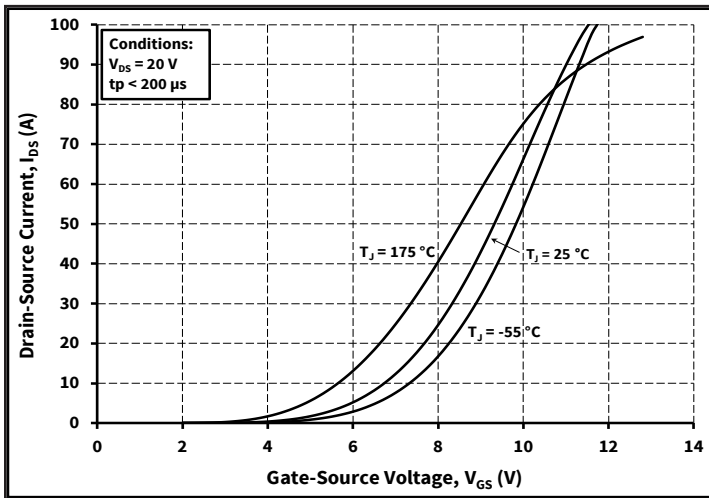


Figure 7. Transfer Characteristic for Various Junction Temperatures

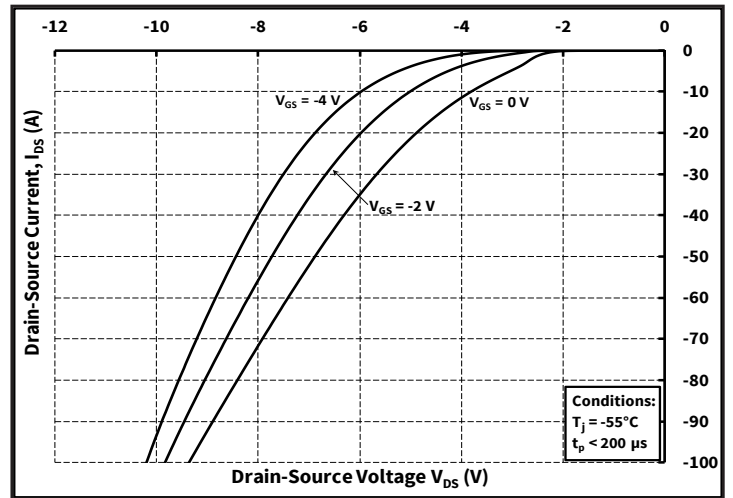
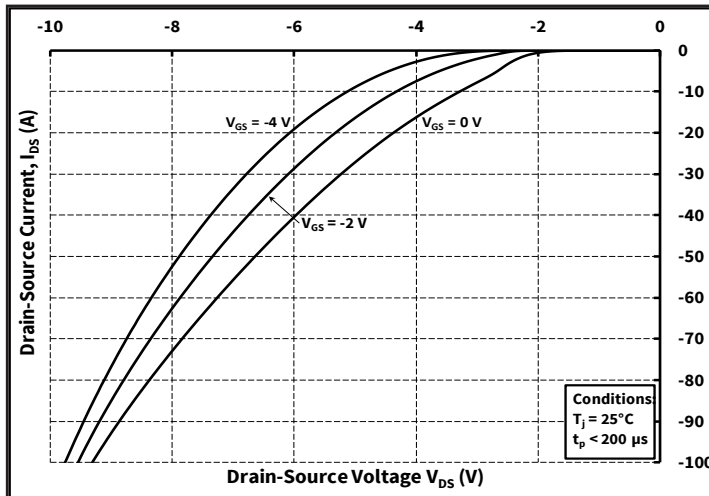
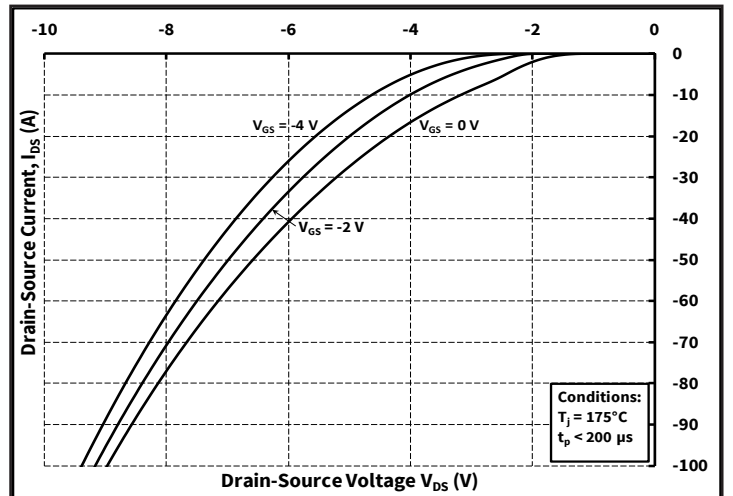
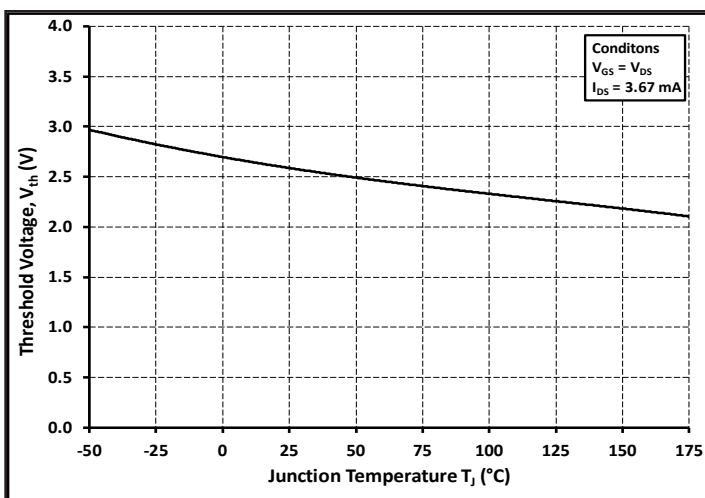
Figure 8. Body Diode Characteristic at  $-55^\circ\text{C}$ Figure 9. Body Diode Characteristic at  $25^\circ\text{C}$ Figure 10. Body Diode Characteristic at  $175^\circ\text{C}$ 

Figure 11. Threshold Voltage vs. Temperature

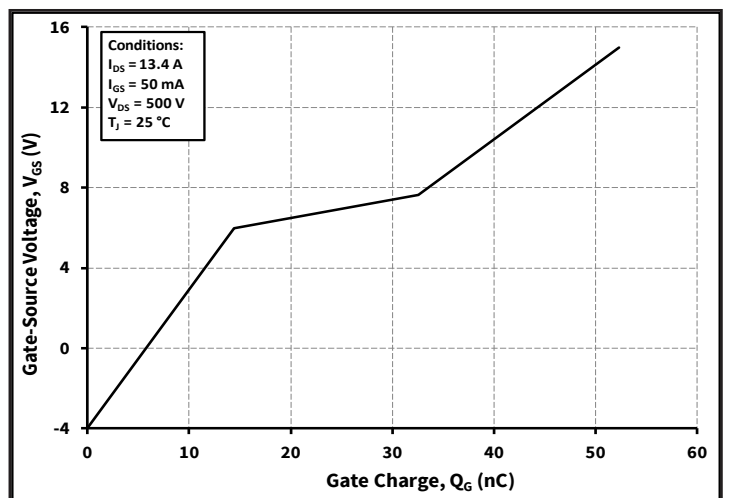


Figure 12. Gate Charge Characteristics

## Typical Performance

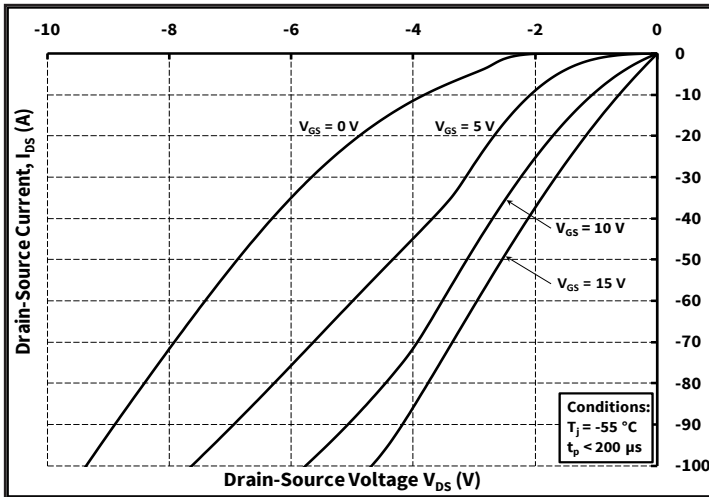
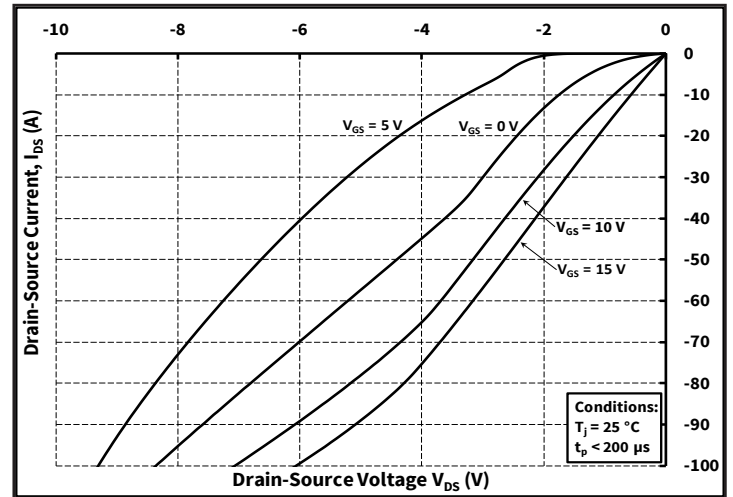
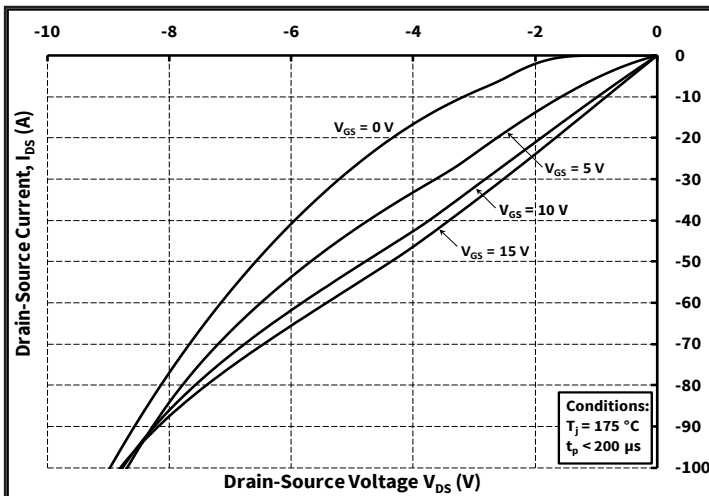
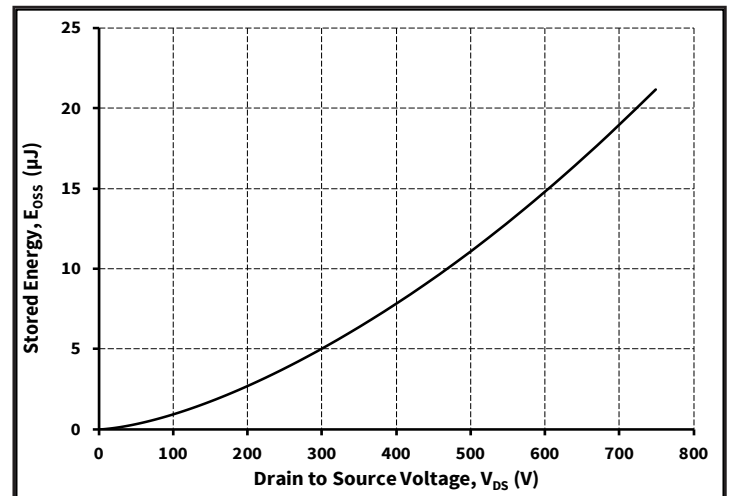
Figure 13. 3rd Quadrant Characteristic at  $-55^{\circ}\text{C}$ Figure 14. 3rd Quadrant Characteristic at  $25^{\circ}\text{C}$ Figure 15. 3rd Quadrant Characteristic at  $175^{\circ}\text{C}$ 

Figure 16. Output Capacitor Stored Energy

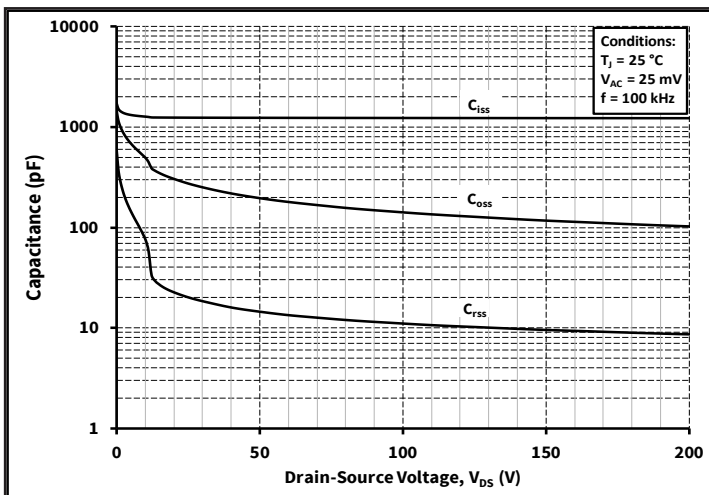


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

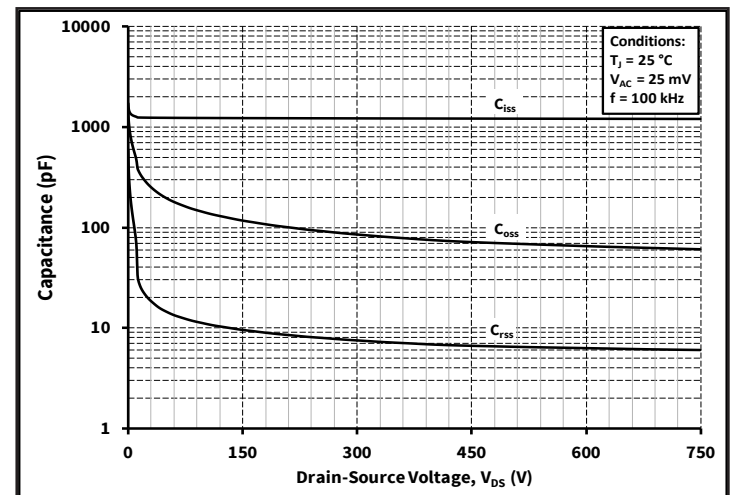


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 750V)

## Typical Performance

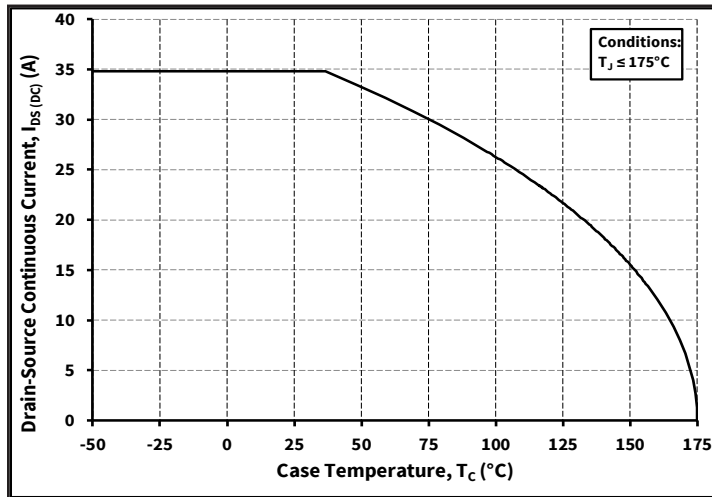


Figure 19. Continuous Drain Current Derating vs. Case Temperature

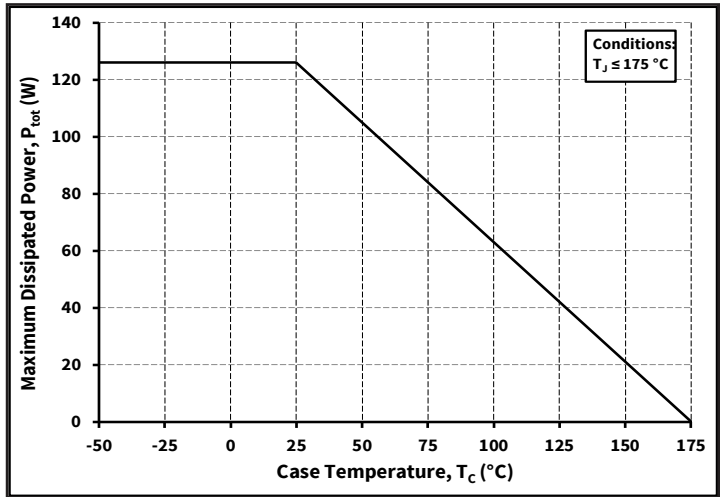


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

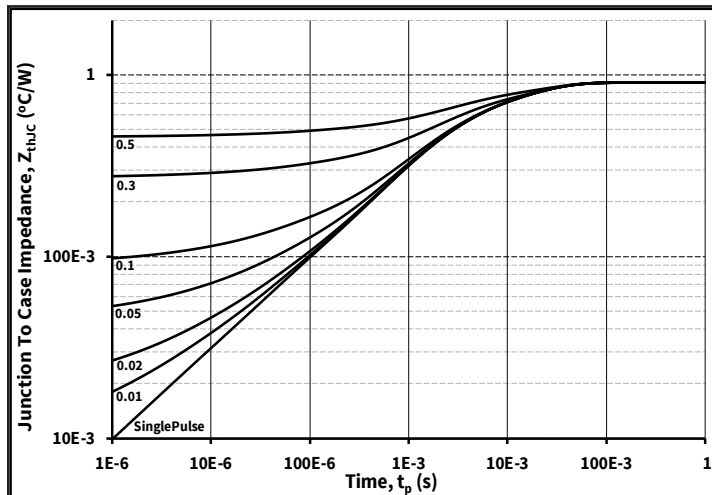


Figure 21. Transient Thermal Impedance (Junction - Case)

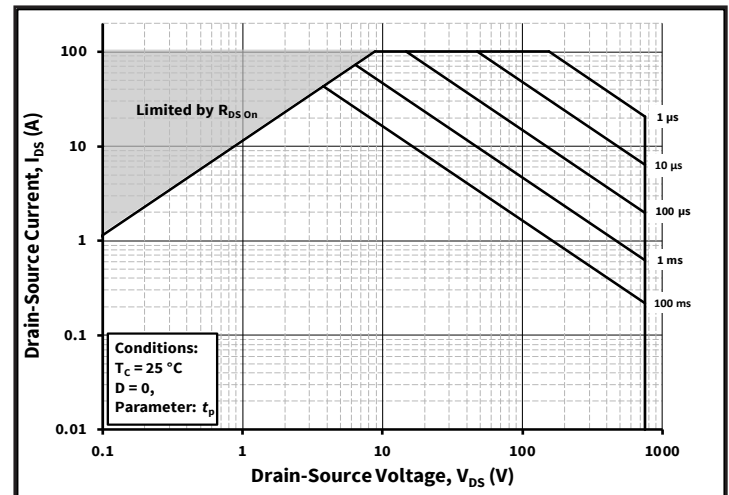
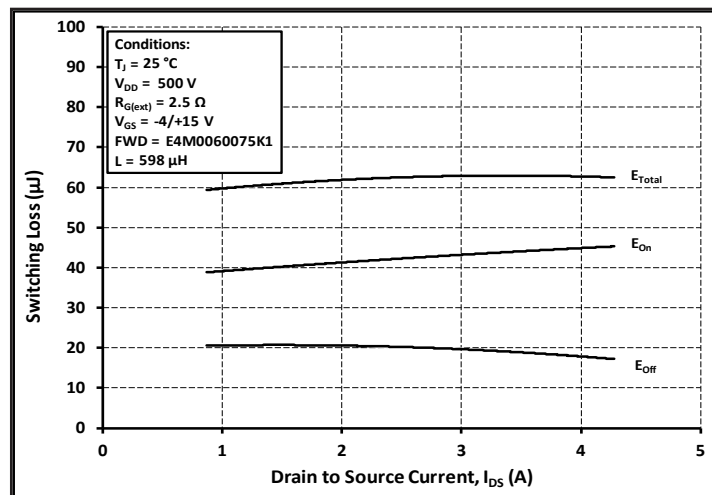
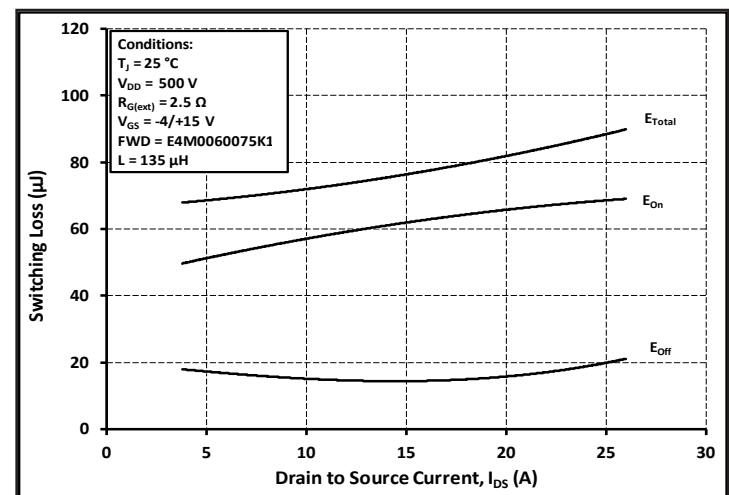


Figure 22. Safe Operating Area

Figure 23. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 500V$ )Figure 24. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 500V$ )

## Typical Performance

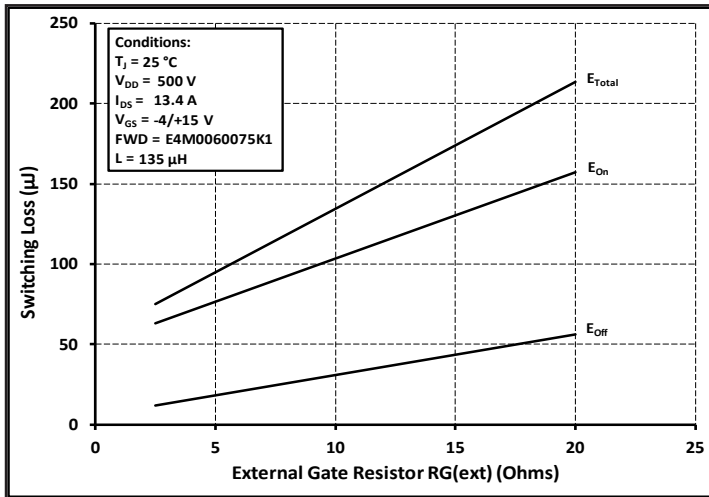
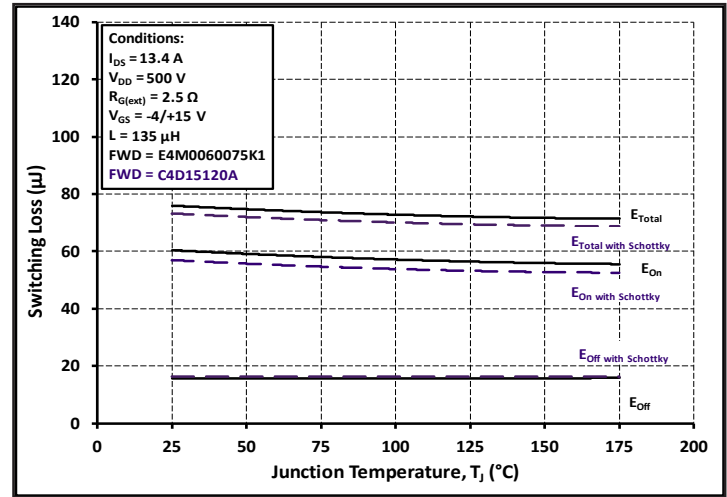
Figure 25. Clamped Inductive Switching Energy vs.  $R_{G(\text{ext})}$ 

Figure 26. Clamped Inductive Switching Energy vs. Temperature

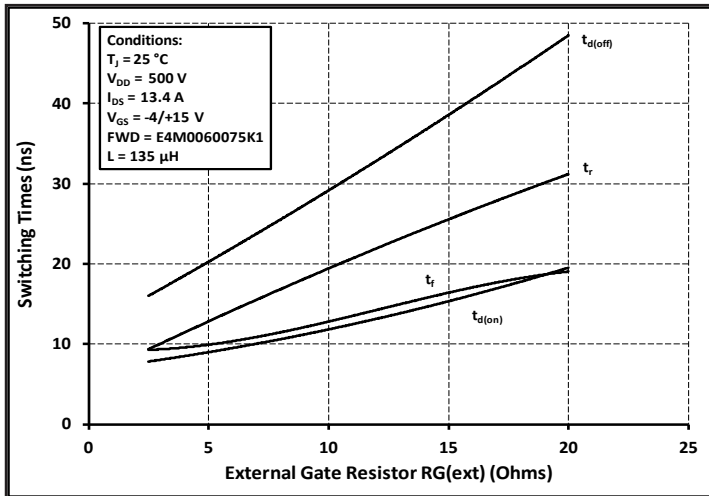
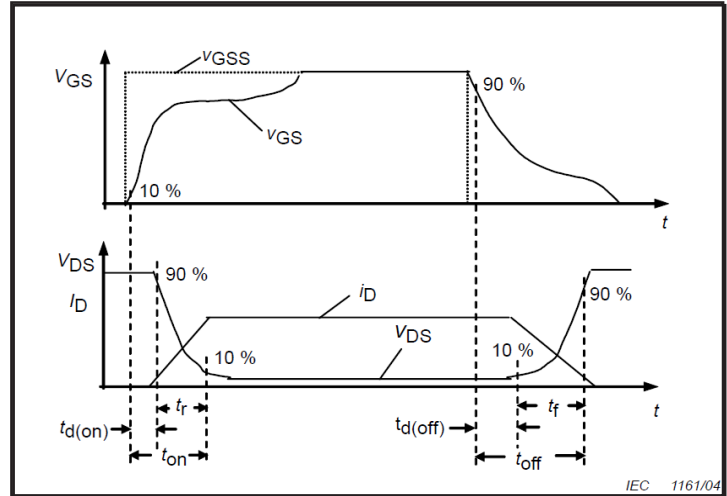
Figure 27. Switching Times vs.  $R_{G(\text{ext})}$ 

Figure 28. Switching Times Definition



## Test Circuit Schematic

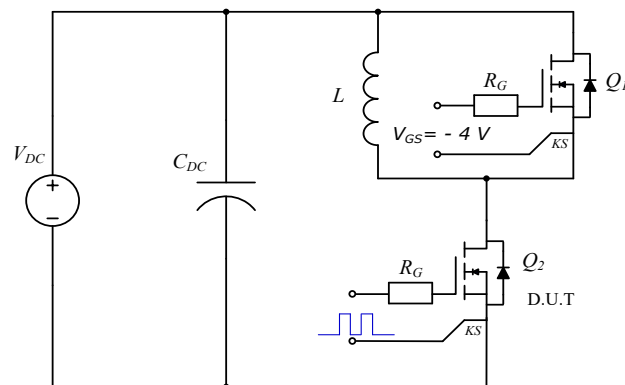
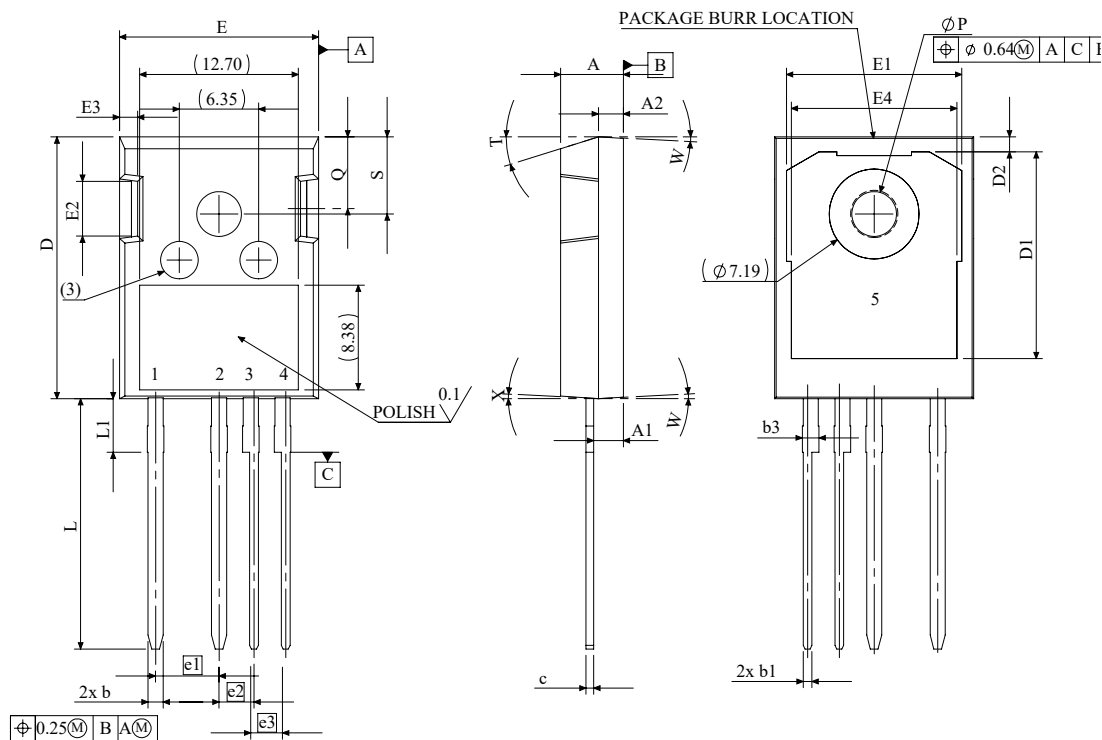


Figure 29. Clamped Inductive Switching Waveform Test Circuit

Package Dimensions



SYMBOL	MIN (mm)	MAX (mm)
A	4.83	5.21
A1	2.22	2.6
A2	1.91	2.16
b	1.10	1.30
b1	0.65	0.79
b3	1.34	1.44
c	0.55	0.68
D	20.76	21.14
D1	16.25	17.65
D2	0.92	1.42
E	15.75	16.13
E1	13.1	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e1	5.08 BSC	
e2	2.79 BSC	
e3	2.54 BSC	
L	19.72	20.32
L1	3.87	4.47
ØP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
T	17.5° REF.	
W	3.5° REF.	
X	4° REF.	

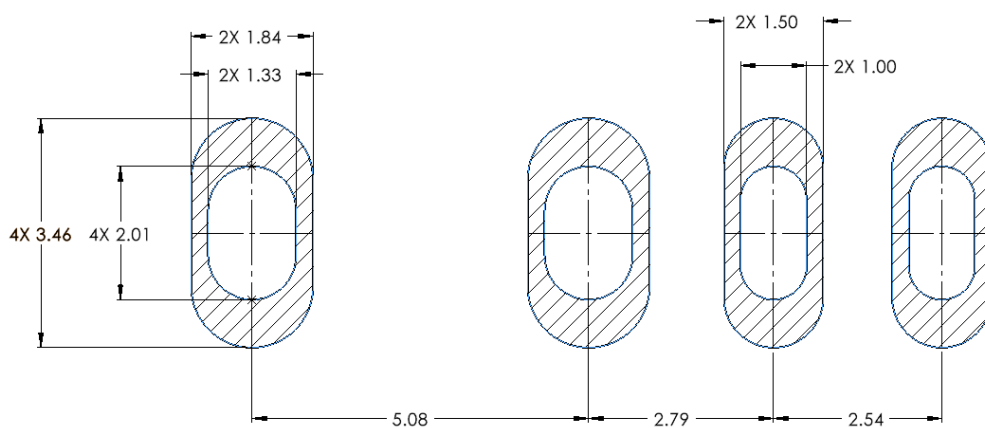
1	DRAIN
2	SOURCE
3	SOURCE
4	GATE
5	DRAIN

- NOTE:
- ALL METAL SURFACES ARE TIN PLATED (MATTE), EXCEPT AREA OF CUT.
  - DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
  - ALL DIMENSIONS ARE LISTED IN MILLIMETERS. ANGLES ARE IN DEGREES.
  - BURR OR MOLD FLASH SIZE (0.5 mm) IS NOT INCLUDED IN THE DIMENSIONS



## Recommended Solder Pad Layout

All dimensions in mm



Revision history

Document Version	Date of release	Descriptiion of changes
1.0	March-2024	Initial datasheet



## Notes & Disclaimer

---

This document and the information contained herein are subject to change without notice. Any such change shall be evidenced by the publication of an updated version of this document by Wolfspeed. No communication from any employee or agent of Wolfspeed or any third party shall effect an amendment or modification of this document. No responsibility is assumed by Wolfspeed for any infringement of patents or other rights of third parties which may result from use of the information contained herein. No license is granted by implication or otherwise under any patent or patent rights of Wolfspeed.

Notwithstanding any application-specific information, guidance, assistance, or support that Wolfspeed may provide, the buyer of this product is solely responsible for determining the suitability of this product for the buyer's purposes, including without limitation for use in the applications identified in the next bullet point, and for the compliance of the buyers' products, including those that incorporate this product, with all applicable legal, regulatory, and safety-related requirements.

This product has not been designed or tested for use in, and is not intended for use in, applications in which failure of the product would reasonably be expected to cause death, personal injury, or property damage, including but not limited to equipment implanted into the human body, life-support machines, cardiac defibrillators, and similar emergency medical equipment, aircraft navigation, communication, and control systems, aircraft power and propulsion systems, air traffic control systems, and equipment used in the planning, construction, maintenance, or operation of nuclear facilities.

### RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Wolfspeed representative or from the Product Documentation sections of [www.wolfspeed.com](http://www.wolfspeed.com).

### REACH Compliance

REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact your Wolfspeed representative to ensure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

### Contact info:

4600 Silicon Drive  
Durham, NC 27703 USA  
Tel: +1.919.313.5300  
[www.wolfspeed.com/power](http://www.wolfspeed.com/power)